

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4406397

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	CHRISTOPH KLEMP	04/04/2017
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	OSRAM OPTO SEMICONDUCTORS GMBH	
<b>Street Address:</b>	LEIBNIZSTR. 4	
<b>City:</b>	REGENSBURG	
<b>State/Country:</b>	GERMANY	
<b>Postal Code:</b>	93055	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	15514652
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(215)656-2498	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	215-656-3381	
<b>Email:</b>	pto.phil@dlapiper.com	
<b>Correspondent Name:</b>	T. DANIEL CHRISTENBURY	
<b>Address Line 1:</b>	ONE LIBERTY PLACE	
<b>Address Line 2:</b>	1650 MARKET STREET, SUITE 4900	
<b>Address Line 4:</b>	PHILADELPHIA, PENNSYLVANIA 19103	
<b>ATTORNEY DOCKET NUMBER:</b>	EHF-17-1104	
<b>NAME OF SUBMITTER:</b>	CAROL CONEY	
<b>SIGNATURE:</b>	/cc/	
<b>DATE SIGNED:</b>	05/10/2017	
<b>Total Attachments: 5</b>		
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(TK/GA)  
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### ASSIGNMENT

For good and valuable consideration, I (We),

Christoph Klemp,  
residing at Boessnerstr. 36 a  
93049 Regensburg  
Germany  
citizen of Germany

hereafter individually or collectively referred to as "Assignor(s)";

Hereby, (I) acknowledge having previously assigned, sold and transferred to **OSRAM Opto Semiconductors GmbH**, a corporation organized and existing under the laws of GERMANY, having its principal place of business at Leibnizstr. 4 in 93055 Regensburg, hereinafter "Assignee", its successors, assigns and legal representatives, or to a predecessor of Assignee, pursuant to (A)(i) the laws of GERMANY or (ii) a Patent & Secrecy Agreement or similar legal document such as, without limitation, an employee agreement executed at the time of entering into the employment of, or executed as a condition of continuing employment with, the Assignee or a predecessor of the Assignee, the entire right, including any and all priority rights, title and interest, in and for the United States and all foreign countries, in and to any and all inventions or improvements which are disclosed in an invention disclosure and/or in the below-identified documents currently filed with this Assignment, already filed or granted for Letters Patent (in which case, any provision of the subject Assignment that is in conflict with or is in addition to any provision in the prior agreement(s) or assignment(s) then this Assignment shall govern, take precedence, and be of legal effect), or

(B)(i) to the extent such laws of GERMANY or such Patent & Secrecy Agreement or similar legal document failed or fails, in whole or part, to have assigned, sold or transferred the entire right (including priority rights), title and interest, in and for the United States and all foreign countries, in and to all inventions or improvements which are disclosed in the below-identified application(s) or pending application(s) or granted Letters Patent, or (ii) if no such agreement(s) exist assigning, selling or transferring any such right (including priority rights), title or interest; then for good and valuable consideration, Assignor(s) now and hereby, effective Nunc Pro Tunc on the filing date of the below identified patent application(s), pending patent application(s) or granted Letter Patent(s), assign, sell and transfer(s) to Assignee, its successors, assigns and legal representatives, the entire right, (including all priority rights), title and interest in and for the United States and all foreign countries, in and to any and all inventions and/or improvements which are disclosed in the following identified; patent application(s), pending patent application(s) or granted Letter Patent(s)

Patent Application Title: Optoelectronic Semiconductor Chip And Method Of Producing  
The Same  
Filing Date: 03/27/2017 (MM/DD/YYYY)  
Filing Number: 15/514,652  
Internal Case Number(s): EHF-17-1104

and in and to said application(s) or granted patents and all applications claiming priority to said application or granted patent, including, without limitation, and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of the inventions and/or improvements; and in and

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to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on the inventions and/or improvements;

(II) Agree that said Assignee may apply for and receive Letters Patent for said inventions and/or improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said inventions and/or improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said inventions and/or improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said inventions and/or improvements and for vesting title to said inventions and or improvements and all applications for patents and all patents on said inventions and/or improvements, in said Assignee, its successors, assigns and legal representatives; and

(III) Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Hakon Kli

Witness Signature

Christoph Klump

Christoph Klump

Horstmann Perlmutter

printed name of witness

April 4<sup>th</sup>, 2017

Date

Companies Representative(s)  
 OSRAM Opto Semiconductors GmbH

Signature

Name

Date

Signature

Name

Date

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Christoph Klemp,  
residing at Boessnerstr. 36 a  
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Patent Application Title: Optoelectronic Semiconductor Chip And Method Of Producing  
The Same

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and in and to said application(s) or granted patents and all applications claiming priority to said application or granted patent, including, without limitation, and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of the inventions and/or improvements; and in and

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to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on the inventions and/or improvements;

(II) Agree that said Assignee may apply for and receive Letters Patent for said inventions and/or improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said inventions and/or improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said inventions and/or improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said inventions and/or improvements and for vesting title to said inventions and/or improvements and all applications for patents and all patents on said inventions and/or improvements, in said Assignee, its successors, assigns and legal representatives; and

(III) Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

\_\_\_\_\_  
 Witness Signature

\_\_\_\_\_  
 Christoph Klemp

\_\_\_\_\_  
 printed name of witness

\_\_\_\_\_  
 Date

Companies Representative(s)  
 OSRAM Opto Semiconductors GmbH

Signature *i.v. Gmelwieser*

Name

Nikolaus Gmelwieser  
 Senior Manager

Date

Intellectual Property  
 11. APR. 2017

Signature *i.v. Lochschmidt*

Name

Andreas Lochschmidt  
 Senior Manager  
 Intellectual Property

Date

11. APR. 2017

EHF-17-1104  
(P2014,1019 US N / 2014P00995WOUS)  
(TK/GA)

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN  
APPLICATION DATA SHEET (37 CFR 1.76)

OPTOELECTRONIC SEMICONDUCTOR CHIP AND METHOD OF PRODUCING THE  
SAME

As the below-named inventor, I hereby declare that:

This declaration is directed to:

- ☐ The attached application, or
- ☒ US Application No. 15/514,652 filed on March 27, 2017.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the  
application.

I hereby acknowledge that any willful false statement made in this Declaration is punishable  
under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

Inventor: Christoph Klemp

Date (Optional): April 4<sup>th</sup>, 2018

Signature: Christoph Klemp